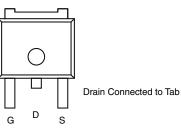


Automotive N-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	30			
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 V$	0.0034			
I _D (A)	100			
Configuration	Single			

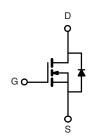
TO-252



Top View

FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g and UIS Tested
- AEC-Q101 Qualified^d
- Material categorization: For definitions of compliance please see <u>www.vishay.com/doc?99912</u>



RoHS COMPLIANT HALOGEN FREE

AUTOMOTIVE

N-Channel MOSFET

ORDERING INFORMATION	
Package	TO-252
Lead (Pb)-free and Halogen-free	SQD100N03-3m4-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V _{DS}	30	V	
Gate-Source Voltage		V _{GS}	± 20	V	
Continuous Drain Current ^a	T _C = 25 °C	- I _D	100		
Continuous Drain Current ^a	T _C = 125 °C		87		
Continuous Source Current (Diode Conduction) ^a		I _S	100	A	
Pulsed Drain Current ^b		I _{DM}	160		
Single Pulse Avalanche Energy	L = 0.1 mH	I _{AS}	58		
Single Pulse Avalanche Current		E _{AS}	168	mJ	
Maximum Dawar Dissinction	T _C = 25 °C	PD	136	W	
Maximum Power Dissipation ^b	T _C = 125 °C		45	vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to + 175	C°	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount ^c	R _{thJA}	50	°C/W
Junction-to-Case (Drain)		R _{thJC}	1.1	0/10

Notes

a. Package limited.

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

c. When mounted on 1" square PCB (FR-4 material).

d. Parametric verification ongoing.

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SQD100N03-3m4



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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT	
Static	-	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_D = 250 \mu A$		30	-	-	V	
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$		3.0	3.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$		-	-	± 100	nA	
		$V_{GS} = 0 V$	V _{DS} = 30 V	-	-	1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 30 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA	
		$V_{GS} = 0 V$	V _{DS} = 30 V, T _J = 175 °C	-	-	150		
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	50	-	-	Α	
		V _{GS} = 10 V	I _D = 20 A	-	0.0028	0.0034	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	I _D = 20 A, T _J = 125 °C	-	-	0.0051		
		V _{GS} = 10 V	I _D = 20 A, T _J = 175 °C	-	-	0.0060		
Forward Transconductanceb	9 _{fs}	V _{DS}	V _{DS} = 20 V, I _D = 20 A		108	-	S	
Dynamic ^b								
Input Capacitance	C _{iss}			-	5879	7349		
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 15 V, f = 1 MHz	-	942	1178	pF	
Reverse Transfer Capacitance	C _{rss}	1		-	413	516		
Total Gate Charge ^c	Qg			-	82.7	124		
Gate-Source Charge ^c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 50 \text{ A}$	-	23.8	-	nC	
Gate-Drain Charge ^c	Q _{gd}	1		-	14.1	-		
Gate Resistance	Rg	f = 1 MHz		0.9	1.86	2.8	Ω	
Turn-On Delay Time ^c	t _{d(on)}			-	13	20		
Rise Time ^c	t _r	V_{DD} = 15 V, R_L = 0.3 Ω I_D \cong 50 A, V_{GEN} = 10 V, R_g = 1 Ω		-	10	15	ns	
Turn-Off Delay Time ^c	t _{d(off)}			-	37	56		
Fall Time ^c	t _f			-	10	15		
Source-Drain Diode Ratings and Chara	acteristics ^b							
Pulsed Current ^a	I _{SM}			-	-	160	Α	
Forward Voltage	V _{SD}	I _F = 30 A, V _{GS} = 0 V		-	0.84	1.2	V	

Notes

a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%.$

b. Guaranteed by design, not subject to production testing.

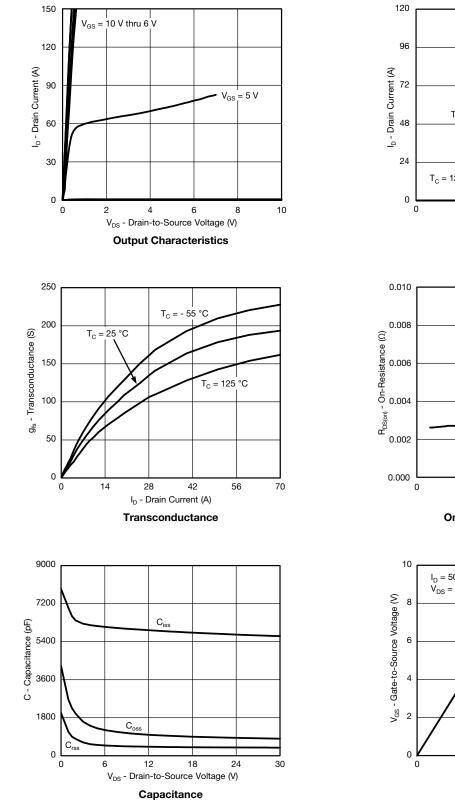
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

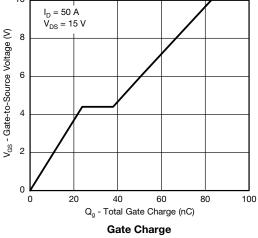




TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



T_C = 25 °C T_C = 125 °C 55 °C 2 6 4 8 10 V_{GS} Gate-to-Source Voltage (V) **Transfer Characteristics** V_{GS} = 10 V 20 40 60 80 100 I_D - Drain Current (A) **On-Resistance vs. Drain Current**



S12-2906-Rev. A, 10-Dec-12

Document Number: 62549

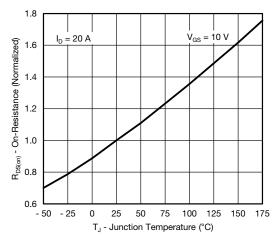
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SQD100N03-3m4

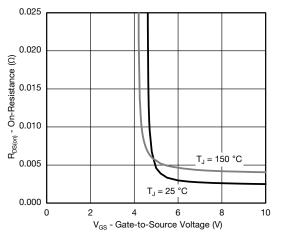


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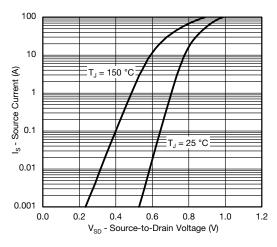
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



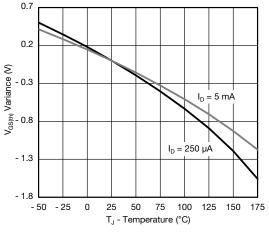
On-Resistance vs. Junction Temperature



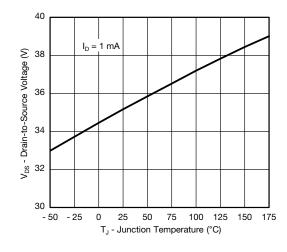
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage







Drain Source Breakdown vs. Junction Temperature

S12-2906-Rev. A, 10-Dec-12

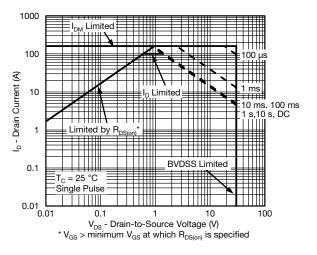
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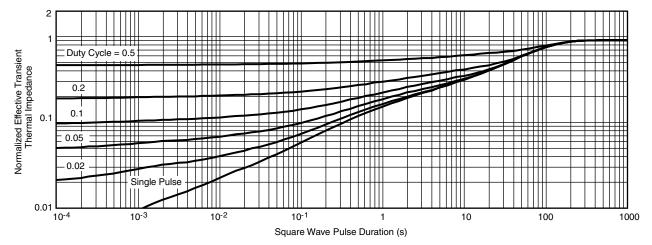




THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



Safe Operating Area

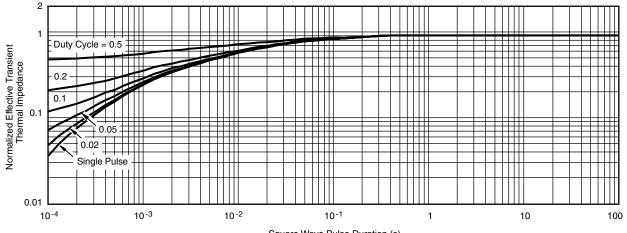


Normalized Thermal Transient Impedance, Junction-to-Ambient





THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Case

Note

The characteristics shown in the two graphs

- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)

- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg262549.





Е b3 Ľ Δ ŝ b2 e1 Б E1

C2 т gage plane height (0.5 mm)

-C

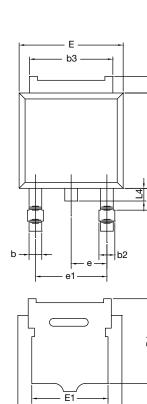
- A1

TO-252AA Case Outline

	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	4.10	-	0.161	-	
Е	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28 BSC 0.090 BSC				
e1	4.56	4.56 BSC		0.180 BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.01	1.52	0.040	0.060	
ECN: T13-0592-Rev. A, 02-Sep-13 DWG: 6019					

Note

• Dimension L3 is for reference only.





RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

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